1.6X0.8mm SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

AP1608MBC

BLUE

Features

- •1.6mmX0.8mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS / REEL .
- •RoHS COMPLIANT.

Description

The Blue source color devices are made with GaN on SiC Light Emitting Diode.

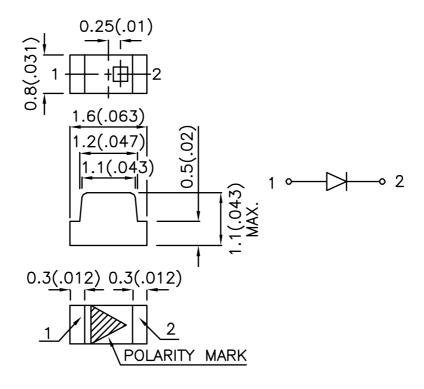
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
- 3. Specifications are subject to change without notice.

SPEC NO: DSAD0923 APPROVED: J. Lu REV NO: V.3 CHECKED: Allen Liu DATE: MAR/10/2005 DRAWN: B.H.LI PAGE: 1 OF 4 ERP: 1203000018

Selection Guide

Part No.	Dice	Lens Type	lv (m @ 20	,	Viewing Angle
			Min. Typ.		201/2
AP1608MBC	BLUE (GaN)	WATER CLEAR	4	10	120°

Note

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	430		nm	IF=20mA
λD	Dominant Wavelength	Blue	466		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	60		nm	IF=20mA
С	Capacitance	Blue	100		pF	VF=0V;f=1MHz
VF	Forward Voltage	Blue	3.8	4.5	V	IF=20mA
IR	Reverse Current	Blue		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	-40°C To +85°C		

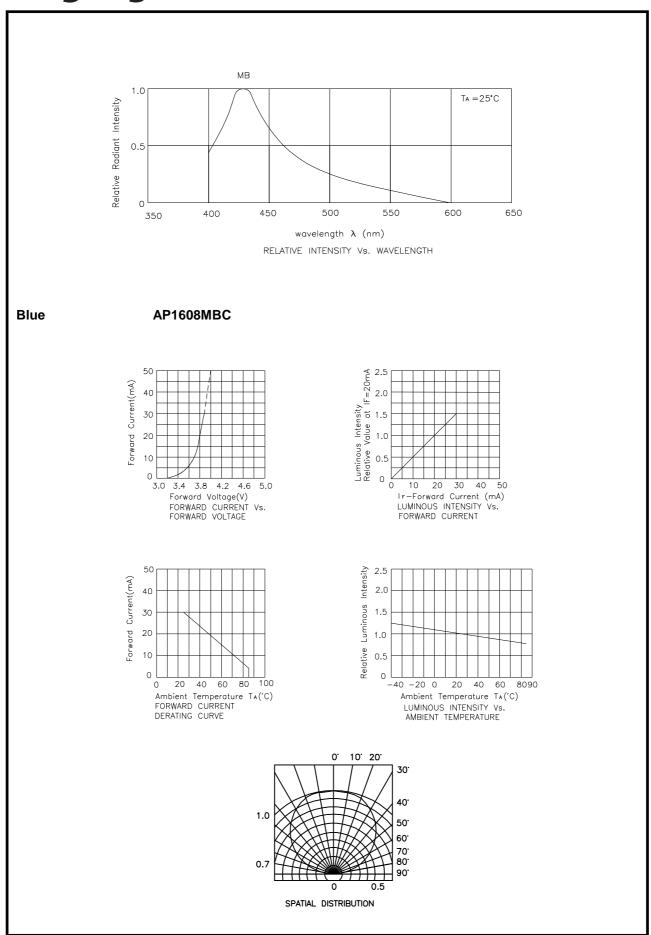
Note

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

 SPEC NO: DSAD0923
 REV NO: V.3
 DATE: MAR/10/2005
 PAGE: 2 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: B.H.LI
 ERP: 1203000018

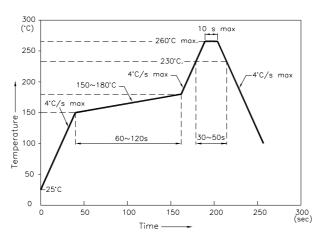
^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.



SPEC NO: DSAD0923 APPROVED: J. Lu REV NO: V.3 CHECKED: Allen Liu DATE: MAR/10/2005 DRAWN: B.H.LI PAGE: 3 OF 4 ERP: 1203000018

AP1608MBC

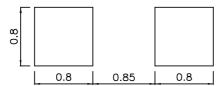
Reflow Soldering Profile For Lead-free SMT Process.



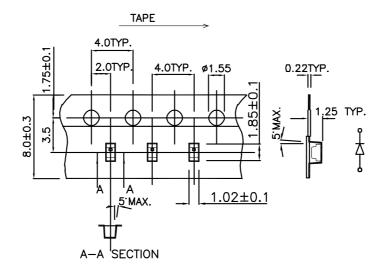
NOTES:

- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

- If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:
- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

 SPEC NO: DSAD0923
 REV NO: V.3
 DATE: MAR/10/2005
 PAGE: 4 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: B.H.LI
 ERP: 1203000018